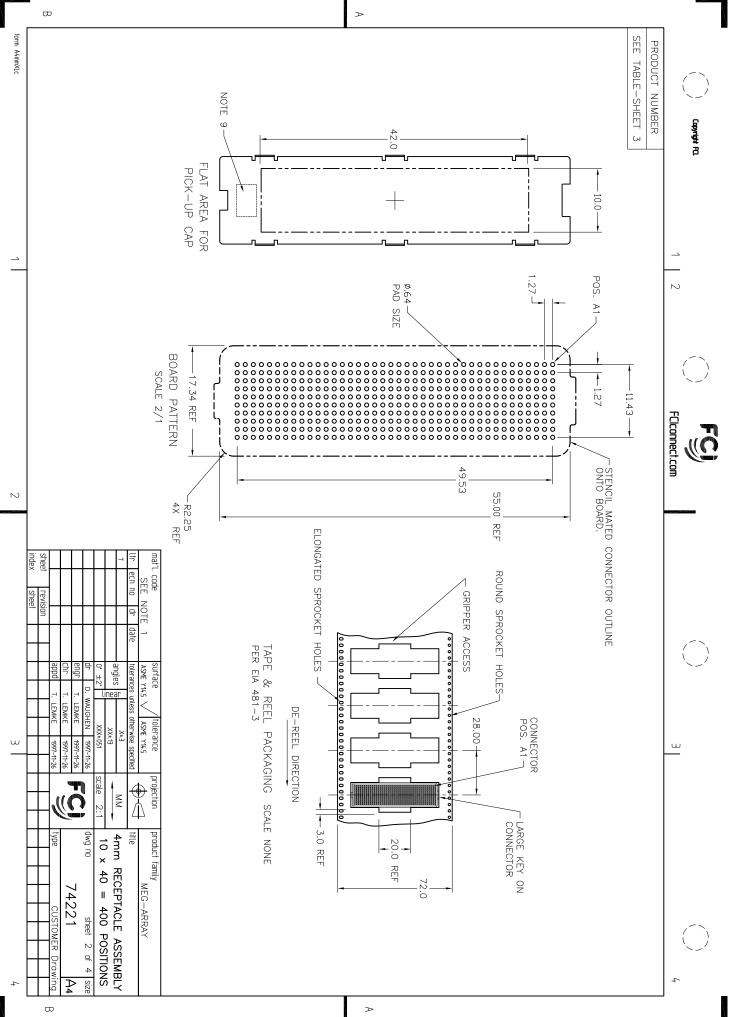


STATUS:Released Pri 2015



PDS: Rev :T STATUS:Released

Printed: Oct 22, 2015

	σ		74221	-742	A -742	-74221-	-74221-	-74221	742	742	742	742	742	742	742	742	742	742	742	742	742	742	PRODUCT	
	MATED AND .		21-501LF	74221-501	74221-401LF	21-401	21-301LF	21-301	74221-A01LF	74221-A01	74221-291LF	74221-291	74221-201LF	74221-201	74221-191LF	74221-191	74221-101LF	74221-101	74221-091LF	74221-091	74221-001LF	74221-001	JCT NUMBER	Copyright FC.
	MATE DIM. A PLUG AS 4.0 84 10.0 84 10.	PLUG ASSY DIM. A REF MATED HGT. AFTER REFLOW	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES	PICK-UP CAP	
~	MATED HEIGHT TABLE PLUG ASSY P/N RECPT. ASSY P/N 84740 74221 84520 74221 FR REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) IR PASTE STENCIL THICKNESS. SEE NOTE 3. - MATED CONNECTORS SCALE NONE		SPECIAL	SPECIAL	30µ" (.76µm) SPECIAL	30µ" (.76µm) SPECIAL	15µ" (.38µm) SPECIAL	15µ" (.38µm) SPECIAL			GXI SPECIAL		AU SPECIAL		ואט (יואעמיי) אטר		- אטע (דוועסיי) אט	176	()	15µ" (.38µm) GXT		15" (38m) A.	CONTACT PLATING	
)	(METAL-DEFINED) = 3. NE	PCB	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	Sppb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SnAgCu LEAD FREE	SnPb	SOLDER BALL	FC) FCIconnect.com
	mat'i, code SEE NOTE Itir ecn no dr T T Sheet revision		5, 7, 8	5 AND 8	7 AND 8	œ	7 AND 8	œ	8 AND 7	00	5 AND 7	IJ	5 AND 7	U	7		7		7		7		NOTES	
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ے ر	ance p : Y14,5 *3 *3 *997-11-26 1997-11-26 1997-11-26 1997-11-26																							<u> </u>
	roduct family MEG-ARRAY ittle 4mm RECEPTACLE ASSEMBLY 10 × 40 = 400 POSITIONS 10 × 40 POSI																							4

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• 1 2		<ul> <li>(5.) PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY). THE</li> <li>(6) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS</li> </ul>	) NO TIN/LEAD OR FLUX ABOVE TERMINAL SHOULDE	PLATING CONTACT: (SEE TABLE ON SHEET 3) SOLDER BALL: (SEE TABLE ON SHEET 3) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE	SEE TABLE-SHEET 3 NOTES: (1.) MATERIAL: HOUSING: LCP, MEETS UL94 V-0 OR BETTER. CONTACT: COPPER ALLOY	
± +	mart1. code       surface       Interance       projection       product family         SEE       NOTE       1       ASME YA5       ASME YA5       Ittle         Itr       ecn       nd       fdie       loterances unless themwase specified       Ittle         Itr       ecn       nd       or       ±x3       MM       MEG-ARRAY         Ittr       ecn       nd       or       ±x2       mm       RECEPTACLE ASSEMBLY         Ittr       engr       0. HORCHLER       2011-06-18       MM       10 x 40 = 400 POSITIONS         sheet       revision       engr       0. HORCHLER       2011-06-18       FG       Mug no       Sheet 4 of 4 size         index       sheet       engr       0. HORCHLER       2011-06-18       Fg       Type       CUSTOMER Drawing	11. –301, –301LF, –401, –401LF, –501, –501LF ARE OBOSOLETE	10. A TRIANGLE SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CUURRENT DRAWING REVISION.	IN THE SEVENTH CHARACTER POSITION. (8) 74221-A01, -A01LF, HAVE CUSTOMER SPECIAL PLATING. (9) CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN.	(7) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X"	